CHIP-TYPE MICRO-CONNECTOR AND METHOD OF PACKAGING THE SAME

Abstract of Disclosure

The chip-type micro-connector includes a package substrate, a micro-connector disposed on the package structure, a plurality of chips, and a cap layer disposed on the micro-connector and the chips. The micro-connector includes a connection substrate, a plurality of connecting wires disposed in the connection substrate, and a plurality of contact pads exposed on a surface of the connection substrate and respectively connected to each connecting wire. The chips are coupled to one another via the contact pads and the connecting wires. The cap layer packages the micro-connector and the chips on the package substrate.

(Fig. 2)